Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTIONS:**

1. **BALANCE**
2. **INPUT-**
3. **INPUT+**
4. **V-**
5. **BALANCE**
6. **OUTPUT**
7. **V+**

**.073”**

**.042”**

**DIE ID**

 **2 1 7**

 **3 4 5 6**

**1**

**5**

**6**

**C**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004” X .004”**

**Backside Potential: V-**

**Mask Ref: 156 C**

**APPROVED BY: DK DIE SIZE .042 X .73” DATE: 8/30/21**

**MFG: TI / NSC THICKNESS .014” P/N: LF156A**

**DG 10.1.2**

#### Rev B, 7/19/02